Features

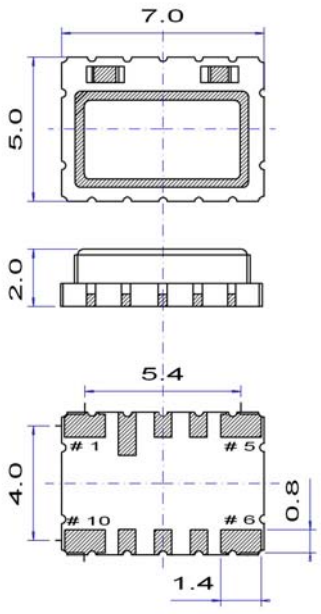
Applications: transmission, TDM networks, SDH, SONET, wireless communications, IEEE 1588v2, SyncE, STRATUM III, wireless backhaul, metro carrier Ethernet, femtocells, picocells
Holdover stability: ±0.37 ppm over 24 h
Overall stability: ±4.60 ppm including 20 years aging
Output signal: CMOS

Specification

Parameter	Specification	
Frequency range	9.83040 ~ 32.0 MHz	
Standard frequencies	10.0, 12.80, 16.3840, 19.440, 20.0, 25.0, 26.0 & 32.0 MHz	
Frequency stability:	≤ ±4.60 ppm	overall stability including 20 years aging
vs. temperature	≤ ±0.28 ppm	-40 ~ +85 °C
vs. aging	≤ ±3.0 ppm	20 years
Holdover stability ([1])	≤ ±0.37 ppm	over 24 hours
Frequency tolerance ex. factory	≤ ±0.50 ppm	@ +25 °C
Supply voltage	+3.3 V or +5.0 V	±5 %
Supply current	< 6 mA	
Output signal	CMOS	
Output load	15 pF	±5 %
Frequency pulling range	±5 ppm	
Voltage control (Vc)	+1.5 V ±1.0 V	
Input impedance	> 100 kΩ	
Phase noise @ 19.440 MHz carrier frequency	-150 dBc/Hz	@ 10 kHz
Operating temperature range	0 ~ +70 °C -40 ~ +85 °C	indoor use outdoor use
Storage temperature range	-55 ~ +125 °C	
Packaging units	tape & reel tape only	500 or 1'000 pieces < 500 pieces

([1]) Including: frequency stability, vs temperature, supply change of ±5 % and aging over 24 hours

Outline Dimensions & PIN Function & Solder Pattern

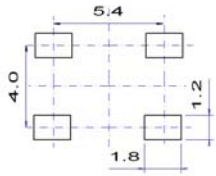


Pin function

# 1	Vc (voltage control)
# 5	GND
# 6	Output
# 10	Vdc

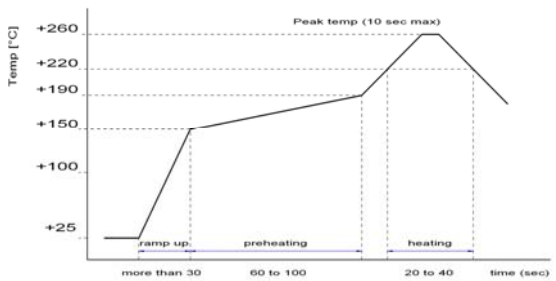
All other pins are not connected

Example for solder pattern



Do not design any conductive path between the pattern

Example for IR reflow soldering temperature



Performance Graphs

Frequency deviation vs. temperature, measured over -20 to +70 °C
(For indoor application)